

SEMICONDUCTOR COMPONENT

Cross-Reference to Related Application:

This application is a continuation of copending International  
5 Application No. PCT/DE00/01251, filed April 20, 2000, which  
designated the United States.

Background of the Invention:

Field of the Invention:

The invention relates to a voltage-controlled semiconductor  
10 component in which a high voltage is present between the  
terminals forming the load path.

The costs in the manufacture of a grid power supply constitute  
a fundamental problem. Suitable selection of a grid power  
supply is dependent on the application, just like the  
15 components that are intended to be used. Switched-mode grid  
power supplies, in particular, are being used more and more  
often. This is due, *inter alia*, to the fact that many complex  
circuit configuration of a switched-mode power supply can be  
combined on a single integrated semiconductor chip. This  
20 enables cost-effective manufacture. A semiconductor chip of  
this type has, in particular, a power switching device and a  
drive configuration for the power switching device. In this  
case, the load terminals of the power switching device are